Product / Package Information

Package	LFCSP - Punched
Body Size (mm)	4 X 4 X 0.85 (2.1 EP)
Lead Count	24
Terminal Finish	100 Sn
MS Number	MS000522D

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.55E-02	86.91	869100	45.31	453107
Thermosets	Epoxy & Phenol Resin	Proprietary	2.28E-03	12.78	127800	6.66	66629
Other inorganic materials	Carbon black	1333-86-4	5.53E-05	0.31	3100	0.16	1616
Subtotal			1.78 E-02	100.00	1000000	52.14	521352

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.31 E-02	97.5	975000	38.39	383921
Copper & its alloys	Iron	7439-89-6	3.16 E-04	2.35	23500	0.93	9253
Copper & its alloys	Zinc	7440-66-6	1.62 E-05	0.12	1200	0.05	473
Copper & its alloys	Phosphorus	7723-14-0	4.04 E-06	0.03	300	0.01	118
Subtotal			1.35 E-02	100.00	1000000	39.38	393765

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	5.47 E-04	100.0	1000000	1.60	15981

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	9.05 E-04	100.0	1000000	2.65	26461

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	6.27 E-05	99.99	1000000	0.18	1834

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.07 E-03	100.0	1000000	3.12	31176

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.51 E-04	77.71	777100	0.73	7329
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	1.00 E-05	3.11	31100	0.03	293
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	1.00 E-05	3.11	31100	0.03	293
Other organic materials	Butyrolactone, gamma-	96-48-0	1.00 E-05	3.11	31100	0.03	293
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	1.00 E-05	3.11	31100	0.03	293
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	1.00 E-05	3.11	31100	0.03	293
Other organic materials	Organosilane	TS ref# 10001	1.00 E-05	3.11	31100	0.03	293
Other inorganic materials	Copper(II) oxide	1317-38-0	1.00 E-05	3.11	31100	0.03	293
Other organic materials	Epoxy resin modifier	TS ref# 10038	1.68 E-06	0.52	5200	0.00	49
Subtotal			3.23 E-04	100.0	1000000	0.94	9431

	Weight (g)	Percentage (%)	PPM
Package Totals	**3.42 E-02**	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.